

- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

### Product Summary



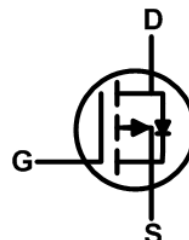
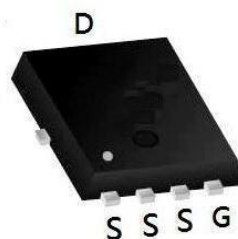
BVDSS	RDSON	ID
-100V	70mΩ	-25A

### Description

The XR20P10F is the high cell density trench P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The XR20P10F meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

### PDFN5060-8L Pin Configuration



### Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$ , unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-Source Voltage		$V_{DS}$	-100	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$T_C = 25^\circ\text{C}$	$I_D$	-20	A
	$T_C = 100^\circ\text{C}$		-11	
Pulsed Drain Current <sup>1</sup>		$I_{DM}$	-72	A
Single Pulse Avalanche Energy <sup>2</sup>		EAS	42	mJ
Total Power Dissipation	$T_C = 25^\circ\text{C}$	$P_D$	102	W
Operating Junction and Storage Temperature Range		$T_J, T_{STG}$	-55 to 150	$^\circ\text{C}$

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>3</sup>	$R_{\theta JA}$	91	$^\circ\text{C/W}$
Thermal Resistance from Junction-to-Case	$R_{\theta JC}$	1.22	$^\circ\text{C/W}$

### Electrical Characteristics (T<sub>J</sub> = 25°C, unless otherwise noted)

Parameter		Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics							
Drain-Source Breakdown Voltage		V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	-100	-	-	V
Gate-body Leakage current		I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	T <sub>J</sub> = 25°C	I <sub>DSS</sub>	V <sub>DS</sub> = -100V, V <sub>GS</sub> = 0V	-	-	-1	μA
	T <sub>J</sub> = 100°C			-	-	-20	
Gate-Threshold Voltage		V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	-1.5	-2	-2.5	V
Drain-Source On-Resistance <sup>4</sup>		R <sub>DS(on)</sub>	V <sub>GS</sub> = -10V, I <sub>D</sub> = -10A	-	70	88	mΩ
			V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -6A		77	97	
Forward Transconductance <sup>4</sup>		g <sub>fs</sub>	V <sub>DS</sub> = -10V, I <sub>D</sub> = -10A	-	28	-	S
Dynamic Characteristics <sup>5</sup>							
Input Capacitance		C <sub>iss</sub>	V <sub>DS</sub> = -50V, V <sub>GS</sub> = 0V, f = 1MHz	-	2859	-	pF
Output Capacitance		C <sub>oss</sub>		-	93	-	
Reverse Transfer Capacitance		C <sub>rss</sub>		-	68	-	
Gate Resistance		R <sub>g</sub>	f = 1MHz	-	4.3	-	Ω
Switching Characteristics <sup>5</sup>							
Total Gate Charge		Q <sub>g</sub>	V <sub>GS</sub> = -10V, V <sub>DS</sub> = -50V, I <sub>D</sub> = -10A	-	53	-	nC
Gate-Source Charge		Q <sub>gs</sub>		-	12	-	
Gate-Drain Charge		Q <sub>gd</sub>		-	10	-	
Turn-On Delay Time		t <sub>d(on)</sub>	V <sub>GS</sub> = -10V, V <sub>DD</sub> = -50V, R <sub>G</sub> = 3Ω, I <sub>D</sub> = -10A	-	8	-	ns
Rise Time		t <sub>r</sub>		-	27	-	
Turn-Off Delay Time		t <sub>d(off)</sub>		-	155	-	
Fall Time		t <sub>f</sub>		-	77	-	
Body Diode Reverse Recovery Time		t <sub>rr</sub>	I <sub>F</sub> = -10A, dI/dt= 100A/μs	-	36	-	ns
Body Diode Reverse Recovery Charge		Q <sub>rr</sub>		-	40	-	nC
Drain-Source Body Diode Characteristics							
Diode Forward Voltage <sup>4</sup>		V <sub>SD</sub>	I <sub>S</sub> = -10A, V <sub>GS</sub> = 0V	-	-0.9	-1.3	V
Continuous Source Current	T <sub>C</sub> = 25°C	I <sub>S</sub>	-	-	-	20	A

Notes:

1. Repetitive rating, pulse width limited by junction temperature T<sub>J(MAX)</sub> = 150°C.
2. The EAS data shows Max. rating . The test condition is V<sub>DD</sub> = -35V, V<sub>GS</sub> = -10V, L = 0.5mH, I<sub>AS</sub> = -23A
3. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 20Z copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
5. This value is guaranteed by design hence it is not included in the production test..

### Typical Performance Characteristics

Fig 1: Output Characteristics

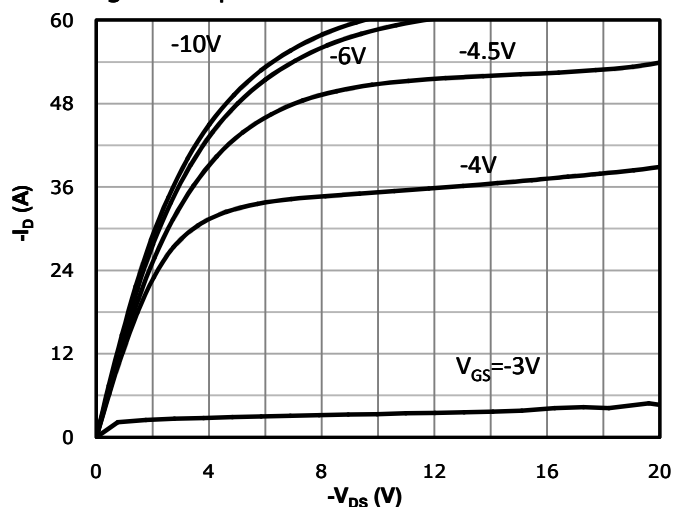


Fig 2: Transfer Characteristics

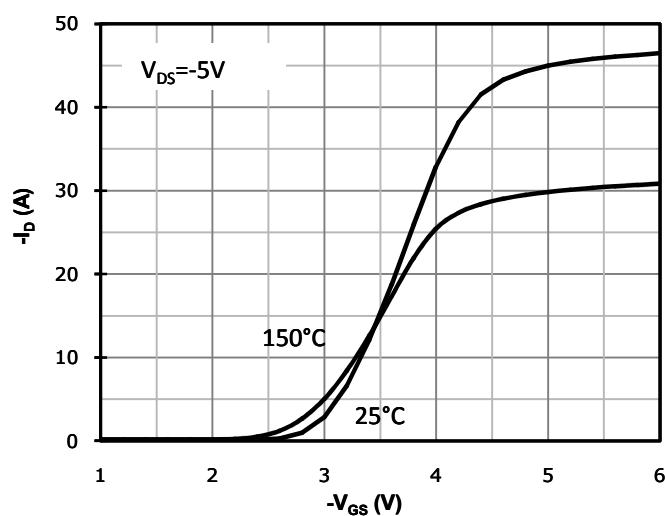


Fig 3:  $R_{DS(on)}$  vs Drain Current and Gate Voltage

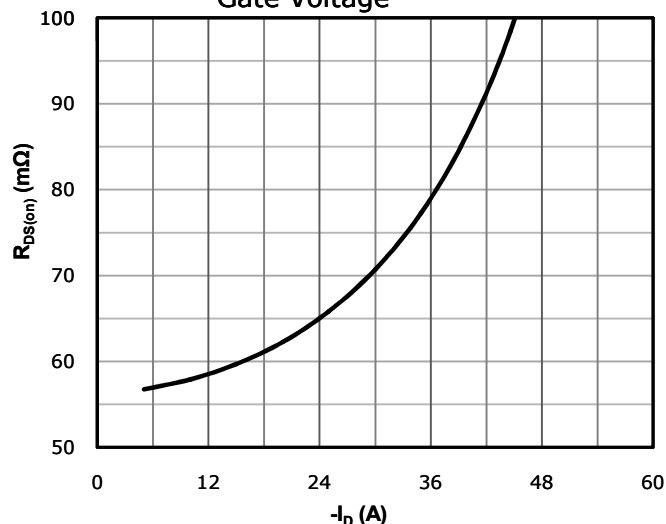


Fig 4:  $R_{DS(on)}$  vs Gate Voltage

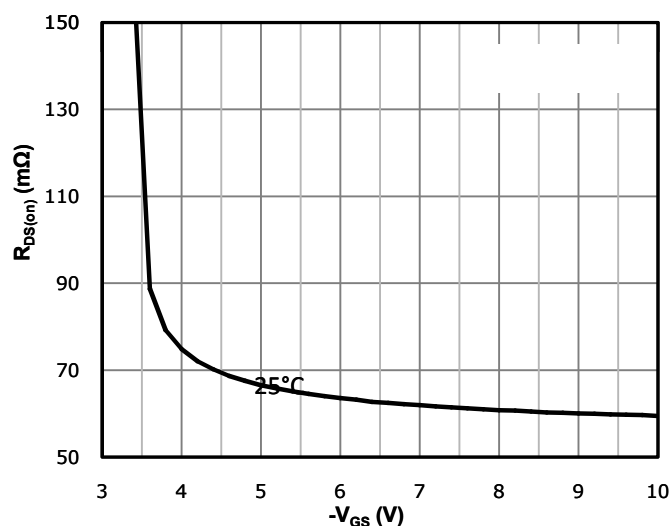


Fig 5:  $R_{DS(on)}$  vs. Temperature

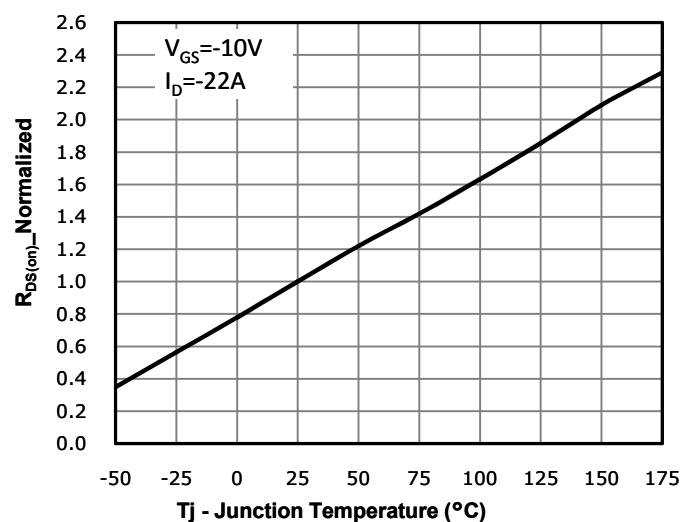


Fig 6: Capacitance Characteristics

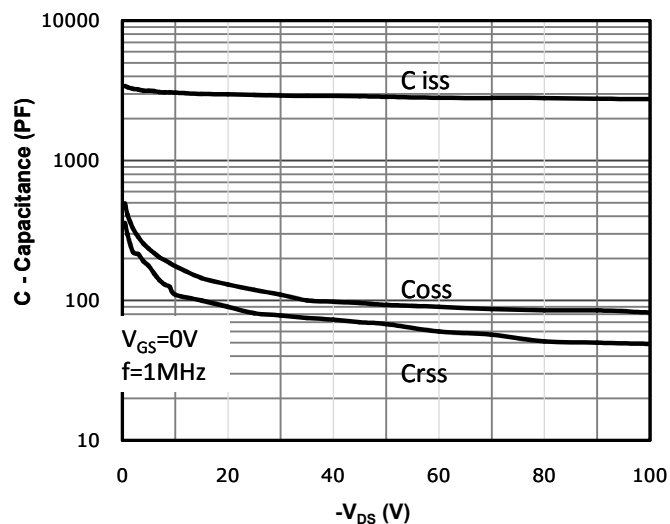


Fig 7: Gate Charge Characteristics

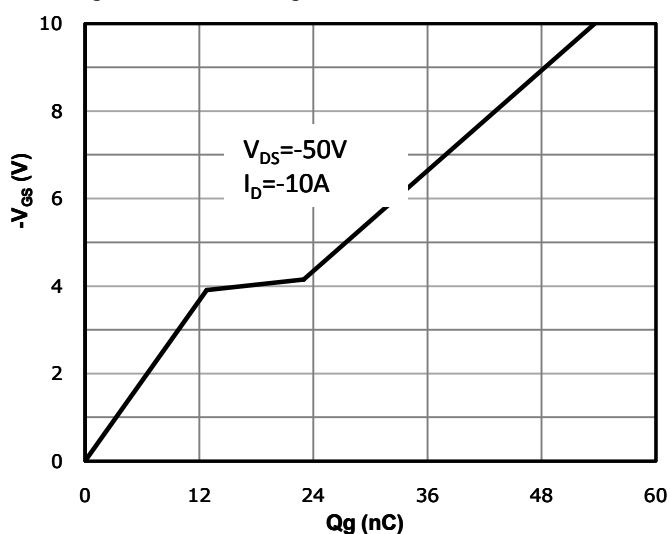


Fig 8: Body-diode Forward Characteristics

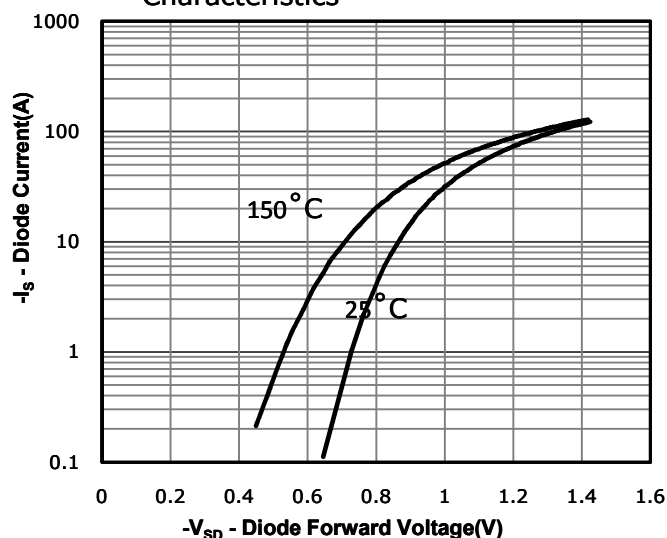


Fig 9: Power Dissipation

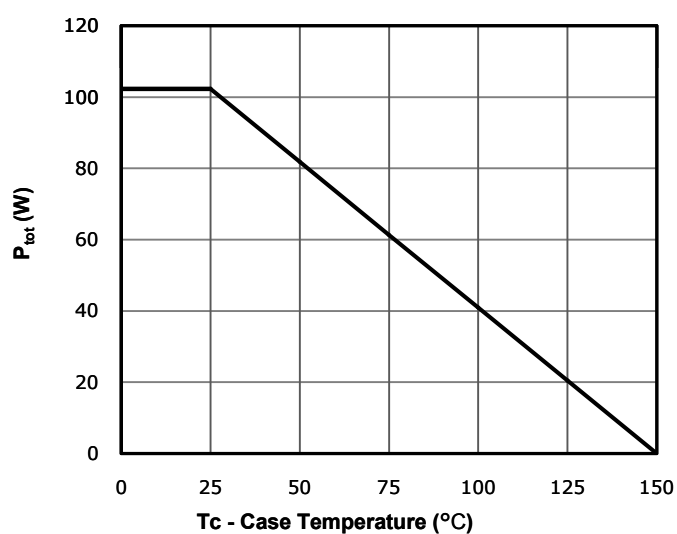


Fig 10: Drain Current Derating

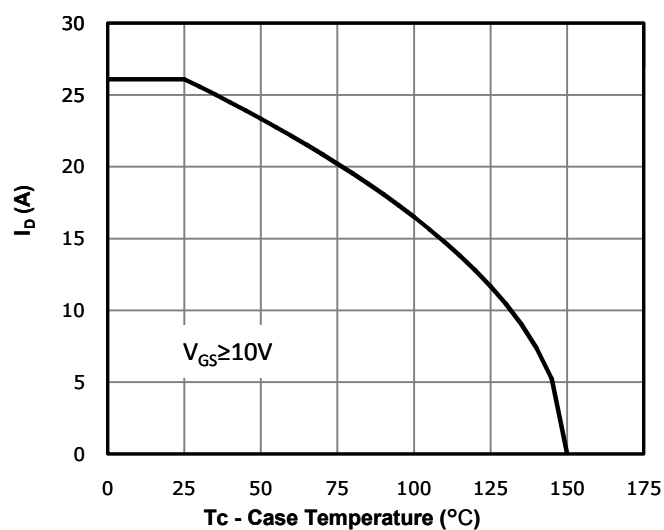


Fig 11: Safe Operating Area

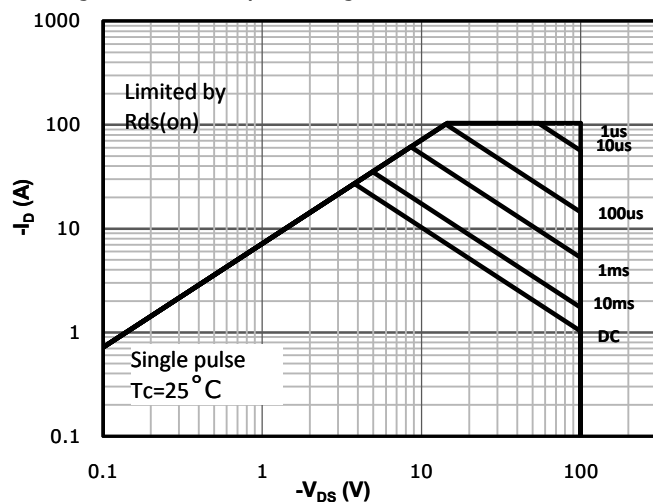
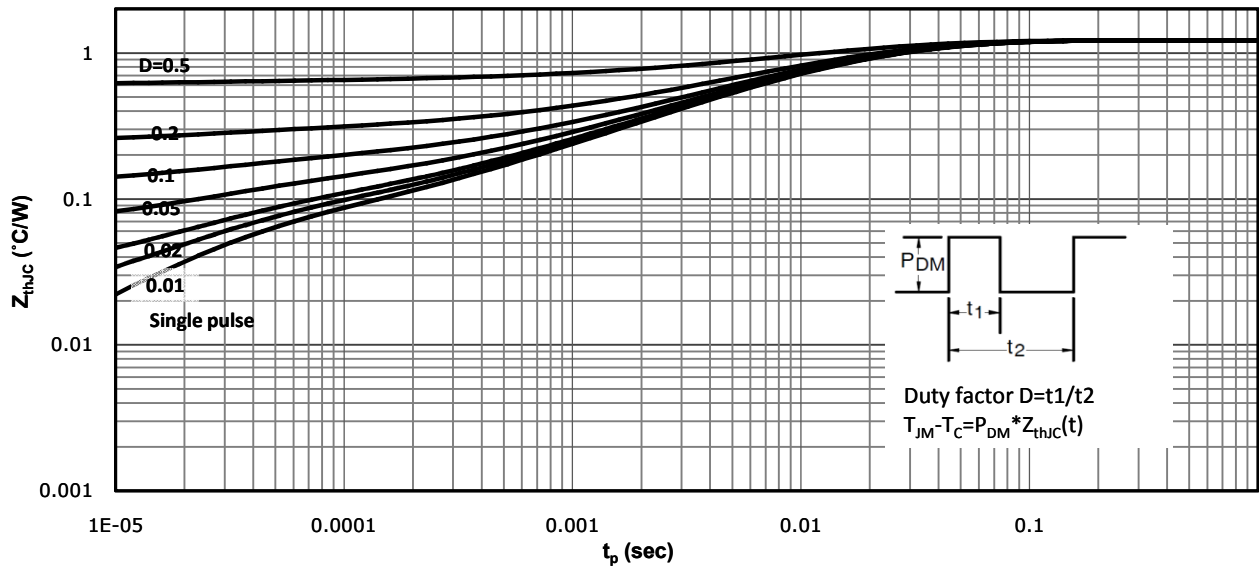
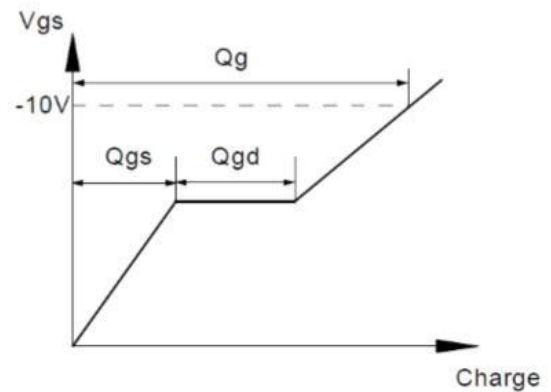
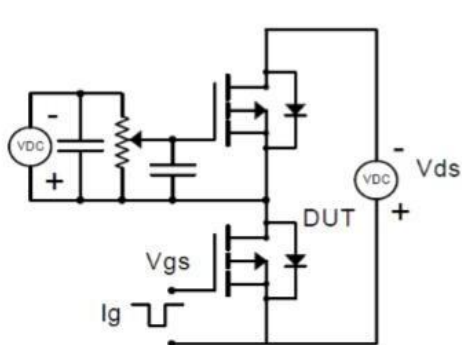


Fig 12: Max. Transient Thermal Impedance

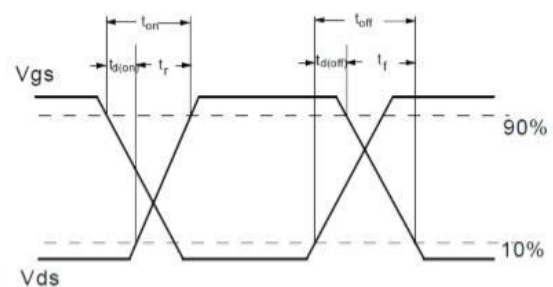
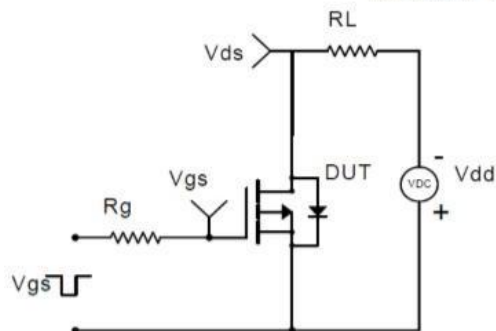


### Test Circuit & Waveform

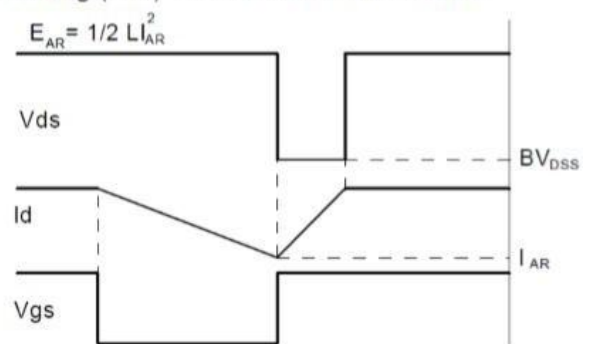
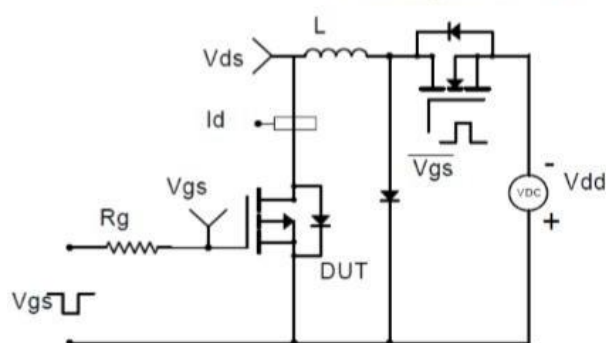
Gate Charge Test Circuit & Waveform



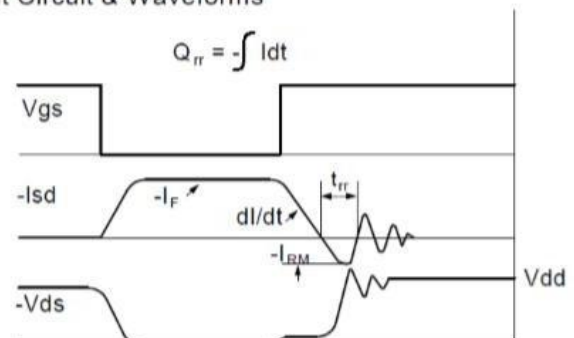
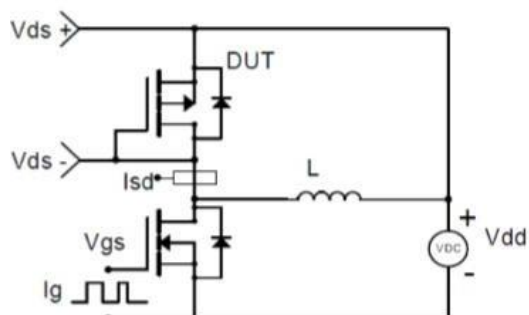
Resistive Switching Test Circuit & Waveforms



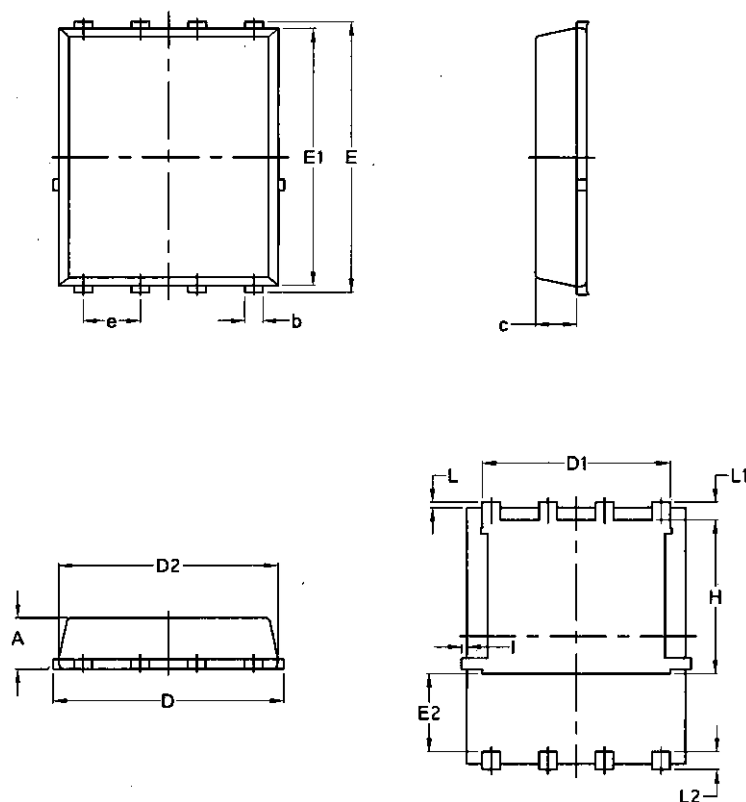
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



### Package Mechanical Data-PDFN5060-8L-Single



Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070